- 2-V to 6-V V<sub>CC</sub> Operation
- Inputs Accept Voltages to 6 V
- Max t<sub>pd</sub> of 11 ns at 5 V
- 3-State Inverting Outputs Drive Bus Lines Directly
- Full Parallel Access for Loading

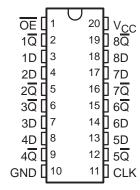
#### description/ordering information

These octal edge-triggered D-type flip-flops feature 3-state outputs designed specifically for driving highly capacitive or relatively low-impedance loads. The devices are particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers.

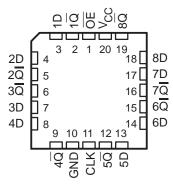
On the positive transition of the clock (CLK) input, the  $\overline{Q}$  outputs are set to the complements of the logic levels set up at the data (D) inputs.

A buffered output-enable ( $\overline{OE}$ ) input can be used to place the eight outputs in either a normal logic state (high or low logic levels) or the high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and increased drive provide the capability to drive bus lines without need for interface or pullup components.

SN54AC534 . . . J OR W PACKAGE SN74AC534 . . . DB, DW, N, NS, OR PW PACKAGE (TOP VIEW)



SN54AC534 . . . FK PACKAGE (TOP VIEW)



OE does not affect internal operations of the flip-flops. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

#### ORDERING INFORMATION

TA	PACKAGE	<u></u> †	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	PDIP – N	Tube	SN74AC534N	SN74AC534N
	COIC DW	Tube	SN74AC534DW	AC524
	SOIC – DW	Tape and reel	SN74AC534DWR	AC534
-40°C to 85°C	SOP - NS	Tape and reel	SN74AC534NSR	AC534
	SSOP – DB	Tape and reel SN74AC534DE		AC534
		Tube	SN74AC534PW	10504
	TSSOP – PW	Tape and reel	SN74AC534PWR	AC534
	CDIP – J	Tube	SNJ54AC534J	SNJ54AC534J
-55°C to 125°C	CFP – W	Tube	SNJ54AC534W	SNJ54AC534W
	LCCC - FK	Tube	SNJ54AC534FK	SNJ54AC534FK

<sup>†</sup> Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



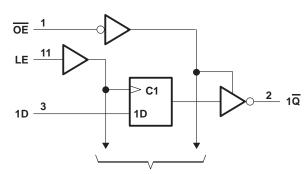
### description/ordering information (continued)

To ensure the high-impedance state during power up or power down,  $\overline{OE}$  should be tied to  $V_{CC}$  through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

## FUNCTION TABLE (each flip-flop)

	INPUTS		OUTPUT
OE	CLK	D	Q
L	1	Н	L
L	$\uparrow$	L	Н
L	H or L	Χ	$\overline{Q}_0$
Н	X	Χ	Z

#### logic diagram (positive logic)



To Seven Other Channels

### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V <sub>CC</sub>		–0.5 V to 7 V
Input voltage range, V <sub>I</sub> (see Note 1)		$10.5 \text{ V to V}_{CC} + 0.5 \text{ V}$
Output voltage range, VO (see Note 1)		$0.5 \text{ V to V}_{CC} + 0.5 \text{ V}$
Input clamp current, $I_{IK}$ ( $V_I < 0$ or $V_I > V_{CC}$ )		±20 mA
Output clamp current, I <sub>OK</sub> (V <sub>O</sub> < 0 or V <sub>O</sub> > V <sub>CO</sub>	c)	±20 mA
Continuous output current, $I_O$ ( $V_O = 0$ to $V_{CC}$ )	-	±50 mA
Continuous current through V <sub>CC</sub> or GND		±200 mA
Package thermal impedance, θ <sub>JA</sub> (see Note 2):	: DB package	70°C/W
	DW package	58°C/W
	N package	69°C/W
	NS package	60°C/W
	PW package	83°C/W
Storage temperature range, T <sub>stg</sub>		–65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
  - 2. The package thermal impedance is calculated in accordance with JESD 51-7.



### recommended operating conditions (see Note 3)

			SN54 <i>A</i>	C534	SN74A	C534		
			MIN	MAX	MIN	MAX	UNIT	
Vcc	Supply voltage		2	6	2	6	V	
		V <sub>CC</sub> = 3 V	2.1		2.1			
ViH	High-level input voltage	V <sub>CC</sub> = 4.5 V	3.15		3.15		V	
		V <sub>CC</sub> = 5.5 V	3.85		3.85			
		V <sub>CC</sub> = 3 V		0.9		0.9		
VIL	Low-level input voltage	V <sub>CC</sub> = 4.5 V		1.35		1.35	V	
		V <sub>CC</sub> = 5.5 V		1.65		1.65		
٧ı	Input voltage	•	0	Vcc	0	Vcc	V	
٧o	Output voltage		QÛ	VCC	0	Vcc	V	
		V <sub>CC</sub> = 3 V	200	-12		-12		
loh	High-level output current	V <sub>CC</sub> = 4.5 V	A.	-24		-24	mA	
		V <sub>CC</sub> = 5.5 V		-24		-24		
		V <sub>CC</sub> = 3 V		12		12		
lOL	Low-level output current	V <sub>CC</sub> = 4.5 V		24		24	mA	
		V <sub>CC</sub> = 5.5 V		24		24		
Δt/Δν	Input transition rise or fall rate			8		8	ns/V	
T <sub>A</sub>	Operating free-air temperature		-55	125	-40	85	°C	

NOTE 3: All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DADAMETER	TEST SOMBITIONS	.,	T,	Δ = 25°C		SN54A	C534	SN74A	C534	
PARAMETER	TEST CONDITIONS	VCC	MIN	TYP I	MAX	MIN	MAX	MIN	MAX	UNIT
		3 V	2.9			2.9		2.9		
	I <sub>OH</sub> = -50 μA	4.5 V	4.4			4.4		4.4		
V		5.5 V	5.4			5.4		5.4		.,
VOH	I <sub>OH</sub> = -12 mA	3 V	2.56			2.4	7	2.46		V
	loυ = -24 mΔ	4.5 V	3.86			3.7	1/5	3.76		
	$I_{OH} = -24 \text{ mA}$	5.5 V	4.86			4.7	9E	4.76		
	I <sub>OL</sub> = 50 μA	3 V			0.1	7	0.1		0.1	
		4.5 V			0.1	$\mathcal{O}_{\mathcal{I}_{2}}$	0.1		0.1	
V		5.5 V			0.1	<sup>3</sup> 0,	0.1		0.1	.,
VOL	I <sub>OL</sub> = 12 mA	3 V			0.36	Yd	0.5		0.44	V
	04 = 4	4.5 V			0.36		0.5		0.44	
	I <sub>OL</sub> = 24 mA	5.5 V			0.36		0.5		0.44	
loz	$V_O = V_{CC}$ or GND	5.5 V			±0.5		±5		±2.5	μΑ
lį	$V_I = V_{CC}$ or GND	5.5 V			±0.1		±1		±1	μΑ
Icc	$V_I = V_{CC}$ or GND, $I_O = 0$	5.5 V			4		80		40	μΑ
C <sub>i</sub>	$V_I = V_{CC}$ or GND	5 V		4.5	·					pF

### SN54AC534, SN74AC534 OCTAL EDGE-TRIGGERED D-TYPE FLIP-FLOPS WITH 3-STATE OUTPUTS

SCAS554D - NOVEMBER 1995 - REVISED OCTOBER 2003

## timing requirements over recommended operating free-air temperature range, $V_{CC}$ = 3.3 V $\pm$ 0.3 V (unless otherwise noted) (see Figure 1)

		T <sub>A</sub> = 25°C		SN54AC534 SN74AC53			C534	
		MIN	MAX	MIN	MAX	MIN	MAX	UNIT
fclock	Clock frequency		70	Ğ.	60		70	MHz
t <sub>W</sub>	Pulse duration, CLK high or low	5		8	7/6	6.5		ns
t <sub>su</sub>	Setup time, data before CLK↑	5		2.8	4	6.5		ns
t <sub>h</sub>	Hold time, data after CLK↑	1		3		1.5		ns

## timing requirements over recommended operating free-air temperature range, $V_{CC}$ = 5 V $\pm$ 0.5 V (unless otherwise noted) (see Figure 1)

		T <sub>A</sub> = 25°C		SN54A	C534	SN74AC534		
			MAX	MIN	MAX	MIN	MAX	UNIT
fclock	Clock frequency		150	.0	75		140	MHz
t <sub>W</sub>	Pulse duration, CLK high or low	3.5		5.5	Ŋ.	4		ns
t <sub>su</sub>	Setup time, data before CLK↑	3.5		5.5	E	4		ns
th	Hold time, data after CLK↑	1		3		1.5		ns

## switching characteristics over recommended operating free-air temperature range, $V_{CC}$ = 3.3 V $\pm$ 0.3 V (unless otherwise noted) (see Figure 1)

	FROM	то	$T_A = 2$	T <sub>A</sub> = 25°C		SN54AC534		SN74AC534	
PARAMETER	(INPUT)	(OUTPUT)	MIN	MAX	MIN	MAX	MIN	MAX	UNIT
f <sub>max</sub>			70		60	SVI	70		MHz
tPLH	0114	-	3	14	2 4	17.5	2.5	16	
<sup>t</sup> PHL	CLK	Q	3	13	2	16.5	2.5	15	ns
<sup>t</sup> PZH	ŌĒ	Q	3	12.5	2	15.5	2.5	14	
t <sub>PZL</sub>	OE	Q	3	12.5	2	15.5	2.5	14	ns
<sup>t</sup> PHZ	ŌĒ	<u>-</u>	2	13.5	1	16.5	1.5	15	no
<sup>t</sup> PLZ	UE	Q	2	12	1	15	1.5	13.5	ns

# switching characteristics over recommended operating free-air temperature range, $V_{CC}$ = 5 V $\pm$ 0.5 V (unless otherwise noted) (see Figure 1)

DADAMETED	FROM	то	T <sub>A</sub> = 25°C		SN54AC534		SN74AC534		UNIT
PARAMETER	(INPUT)	(OUTPUT)	MIN	MAX	MIN	MAX	MIN	MAX	UNII
f <sub>max</sub>			150		75	AE	140		MHz
<sup>t</sup> PLH	01.14	Ια	2.5	10.5	1.5	13.5	2	12	
<sup>t</sup> PHL	CLK	α	2.5	9.5	1.5	12.5	2	11	ns
<sup>t</sup> PZH	ŌĒ	Ια	2.5	10	1.5	13	2	11.5	
<sup>t</sup> PZL	OE	α	2.5	10	1.5	13	2	11.5	ns
<sup>t</sup> PHZ	ŌĒ	Ια	1.5	11.5	1	14	1	12.5	ns
tPLZ	OE	ά	1.5	10	1	12.5	1	11	115

### operating characteristics, V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C

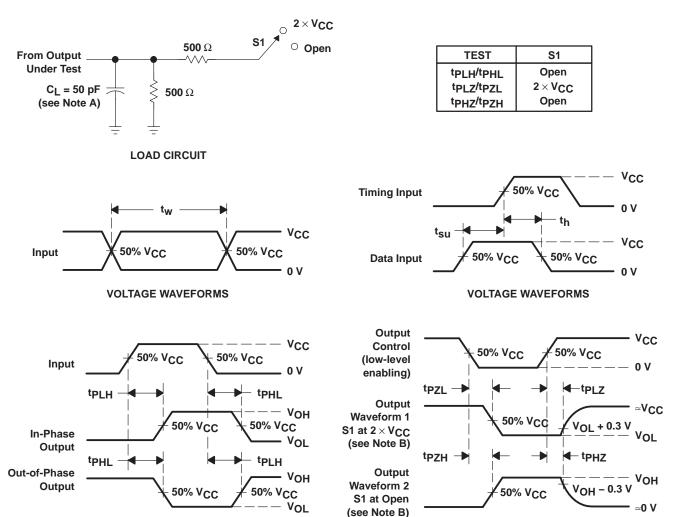
	PARAMETER	TEST CO	ONDITIONS	TYP	UNIT
C <sub>pd</sub>	Power dissipation capacitance	$C_L = 50 pF$ ,	f = 1 MHz	40	pF

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**VOLTAGE WAVEFORMS** 

#### PARAMETER MEASUREMENT INFORMATION



NOTES: A.  $C_L$  includes probe and jig capacitance.

**VOLTAGE WAVEFORMS** 

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  1 MHz,  $Z_O = 50 \,\Omega$ ,  $t_f \leq 2.5 \,$ ns,  $t_f \leq 2.5 \,$ ns.
- D. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms



4-Jun-2007



#### **PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
SN74AC534DBLE	OBSOLETE	SSOP	DB	20		TBD	Call TI	Call TI
SN74AC534DBR	ACTIVE	SSOP	DB	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AC534DBRE4	ACTIVE	SSOP	DB	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AC534DBRG4	ACTIVE	SSOP	DB	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AC534DW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AC534DWE4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AC534DWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AC534DWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AC534DWRE4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AC534DWRG4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AC534N	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74AC534NE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74AC534NSR	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AC534NSRE4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AC534NSRG4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AC534PW	ACTIVE	TSSOP	PW	20	70	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AC534PWE4	ACTIVE	TSSOP	PW	20	70	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AC534PWG4	ACTIVE	TSSOP	PW	20	70	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AC534PWLE	OBSOLETE	TSSOP	PW	20		TBD	Call TI	Call TI
SN74AC534PWR	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AC534PWRE4	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AC534PWRG4	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

(1) The marketing status values are defined as follows: **ACTIVE:** Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.



#### PACKAGE OPTION ADDENDUM

4-Jun-2007

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

**Pb-Free** (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

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(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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#### TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

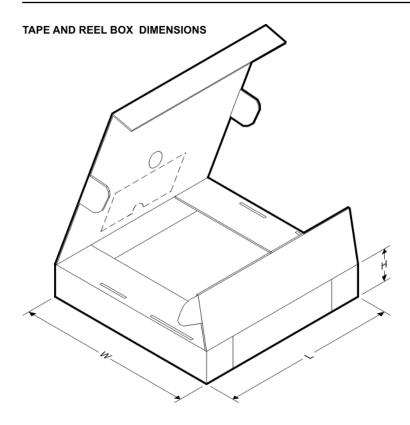
### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74AC534DBR	SSOP	DB	20	2000	330.0	16.4	8.2	7.5	2.5	12.0	16.0	Q1
SN74AC534DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.0	2.7	12.0	24.0	Q1
SN74AC534PWR	TSSOP	PW	20	2000	330.0	16.4	6.95	7.1	1.6	8.0	16.0	Q1





\*All dimensions are nominal

7 th difficition and from that							
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74AC534DBR	SSOP	DB	20	2000	346.0	346.0	33.0
SN74AC534DWR	SOIC	DW	20	2000	346.0	346.0	41.0
SN74AC534PWR	TSSOP	PW	20	2000	346.0	346.0	33.0

### DB (R-PDSO-G\*\*)

### PLASTIC SMALL-OUTLINE

#### **28 PINS SHOWN**



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-150

### **MECHANICAL DATA**

### NS (R-PDSO-G\*\*)

## 14-PINS SHOWN

#### PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



### PW (R-PDSO-G\*\*)

#### 14 PINS SHOWN

### PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

## DW (R-PDSO-G20)

### PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-013 variation AC.



## N (R-PDIP-T\*\*)

### PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



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